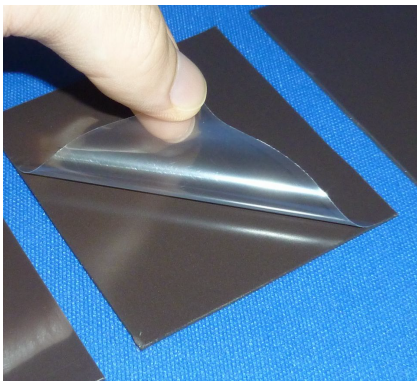
COOLPROVIDE™/ EMPV4



Thermal Interface Material with High Permeability (μ' = 13)

Features

- Excellent EMI absorber performance (μ' = 13) and compliable thermal material (ASKER C 40).
- Have excellent adhesion, performs heat conduction and MHz～GHz range electromagnetic wave attenuation simultaneously.
- Silicone-free, no siloxane outgassing.
- Oil bleeding is reduced compared to silicone-based thermal materials.

(The values below are not guaranteed.)

Test type	Unit	Standard	EMPV4-F
Thermal Conductivity	W/m･K	JIS R 2616 (Hot-wire method)	1.5
		ISO22007-2 (Hot Disc method)	1.4
Color	—	—	Black
Thickness	mm	—	1.0／1.5／2.0 2.5／3.0／3.5
Specific Gravity	—	JIS Z 8807	3.55
Hardness	ASKER C	JIS K 7312	40
	Shore OO	ASTM D 2240	70
Tensile strength	MPa	JIS K 6251	0.51
Elongation rate	%	JIS K 6251	44
Volume Resistivity	Ω･cm	JIS K 6911 compliant	1.0×10^{12}
Breakdown voltage	kV/mm	JIS C 2110-1 compliant	6.0
Withstanding voltage	kV/mm	JIS C 2110-1 compliant	4.2
Dielectric constant	1MHz	Company standard	12.7
Loss tangent	1MHz	Company standard	0.13
Flammability	—	UL94	V-0 equivalent
Permeability (at 10MHz)	—	—	13
Operating temp	℃	—	-40～110
Available max. dimension.※1	mm	—	210×510

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